



Claim 8 (currently amended): A multilayer printed wiring board comprising the film prepared according to claim 4.

Claim 9 (New): The process for producing a surface-adhesive film according to claim 2, wherein the precursor solution is dried at 50°C to 150°C for 5 to 180 minutes, the adhesive aid composition is dried at 50°C to 150°C for 5 to 180 minutes, and the polyimide precursor is heated at 200°C to 500°C for 20 to 300 minutes under a nitrogen stream.